



STAUF SMP 930

1-component hard elastic SMP wood flooring adhesive according to ISO 17178 for parquet $\,$















	Technical Datasheet
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Product number	✓ 125140
Special features	 hard elastic, tension-reducing parquet bonding can be applied to almost all substrate without primers excess adhesive easy to remove water and solvent-free no wood swelling
Suitable for installation of	 vertical finger parquet lamellas, according to DIN EN 14761, from 16 mm thickness solid planks, with relation width/thickness max. 7:1 multiple layer wood flooring according to DIN EN 13489 mosaic parquet according to DIN EN 13488 wood strip flooring raw according to DIN EN 13226, max. 75 x 600 mm, min. 14 mm thickness
Suitable subfloors	 calcium sulphate (flow) floors STAUF levelling compounds for wood flooring chipboards V100 (E1), OSB boards cement floors mastic asphalt screed, only after priming with STAUF VEP 195
Suitable primers	✓ STAUF VDP 130✓ STAUF VPU 155 S✓ STAUF VEP 195
Suitable levelling compounds	 ✓ STAUF XP 40 ✓ STAUF XP 20 ✓ STAUF FZ ✓ STAUF XP 10 ✓ STAUF RM ✓ STAUF PU ✓ STAUF SSP RAPID
Suitable underlays	✓ STAUF polyester fleece✓ STAUF Decoupling/stress relief board
Product properties	✓ aging-resistant

	 elastically deformable suitable on subfloor heating systems not sensitive to frost very well spreadable very low emission fast setting
Color	✓ beige
Required quantities per m²	 1050g with STAUF notched trowel no. 3 1300g with STAUF notched trowel no. 4 1150g with STAUF notched trowel no. 5
Open time	✓ approx. 30 minutes at 20 °C
Accessibility	✓ after approx. 48 hours
Room climate at work site	minimum 15 °C, maximum 75% rel. humidity, preferably max. 65%
Shelf-life	✓ 12 months
Giscode	✓ RS 10
Emicode	✓ EC1 plus
Available Packaging	✓ 18 kg plastic bucket



EXAMINATION OF SUBFLOOR

Prior to processing, the subfloor must be checked according to the standard DIN 18356 or corresponding national standards. The subfloor shall be resistant to pressure and tension, free of cracks, must have sufficient surface strength, be permanently dry, level, clean and free of from contaminants that may prevent adhesion, sinter layers etc. In addition, porosity and grip of surface need to be checked. Also check moisture content and absorption of subfloors as well as temperature, air humidity and subfloor temperature.



SUBFLOOR PREPARATION

It must be ensured that the subfloor is ready for installation by performing proper subfloor preparation, floors must be clean, have sufficient surface strength, must be level, permanently dry and free of cracks. A mechanical pretreatment of the subfloor (sweeping, vacuuming, mechanical brushing, sanding, milling, shot blasting) must be performed depending on type and condition of subfloor. Cracks and joints, except expansion joints and other construction joints, shall be solidly closed with STAUF repair resin and floor brackets. Cavities and indentations can be filled with a non self-levelling STAUF levelling compound. If necessary, make sure subfloors are level, have sufficient absorptive capacity and grip by applying the appropriate STAUF levelling compound.



PROCESSING

Apply adhesive to sub floor using the appropriate STAUF notched trowel, avoid adhesive pooling and excessive layer thickness by evenly raking the notched trowel over adhesive layer. Install wood flooring during specified open time, slide in and press down firmly. In particular with raw wood flooring, avoided pushing adhesive into joints. Adhesive in joints can impair subsequent surface treatment. Depending on the degree of setting, adhesive residues can be removed with the appropriate STAUF cleaners. Please test the effect of the cleaner on the finish of the wood flooring in an inconspicuous area or on a sample prior to applying the cleaner. Hardened adhesive residues can easily be removed mechanically, mostly residue-free. However, longer exposures on finished wood flooring should be avoided to prevent possible

contouring

ACCESSIBILITY



Load bearing capacity depends on room climate and applied quantities of adhesive.



OTHER INFORMATION

The adhesive hardens when reacting with moisture either in the form of air humidity, wood or substrate moisture. The higher the ambient temperature, the faster the adhesive sets. Setting time increases with thickness of the adhesive layer. Plasticizers contained in the adhesive can cause flow asphalts to partially dissolve and may affect the wood flooring finish systems, especially for wood flooring installed without tongue and groove technique. For solid floorboards and solid parquet flooring from a width thickness ratio of 1:7, for thinner solid wood formats of 1:5 (e.g. 10 mm lamparquet), or for laying strongly reacting solid wood types on underfloor heating, it can be useful to bond them in a shear-resistant or hard manner, e.g. with STAUF SPU 570, STAUF PUK 446 or PUK 455.



LIMITATION OF LIABILITY

The foregoing representations are based on the results of our most current product and material testing and are of a non-obligatory advisory nature only since we have no control over the actual quality of workmanship, materials used and worksite conditions. As such, they do not constitute an express or implied warranty of any kind. The same applies to our commercial and technical consultation services which are provided free-of-charge and without obligation. Therefore, we strongly recommend that prior onsite testing be conducted to observe and study the suitability of the product for the intended purpose. With the release of this technical information, all prior technical information (technical data sheets, installation recommendations and other information regarding similar purposes) becomes invalid.

STAUF KLEBSTOFFWERK GMBH. Oberhausener Str. 1. 57234 Wilnsdorf. Germany Fon: +49 (0) 2739 301-0. Fax: +49 (0) 2739 301-200. Email: info@stauf.de